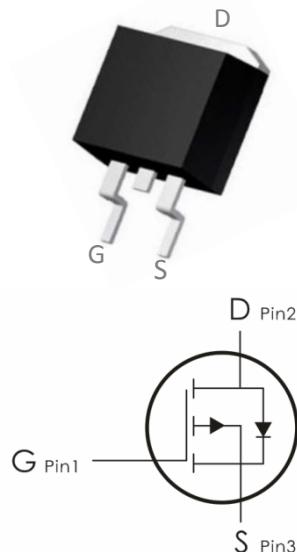


Description:

This P-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.

Features:

- 1) $V_{DS}=-40V, I_D=-110A, R_{DS(on)}<5.3m\Omega @V_{GS}=-10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra $R_{DS(on)}$.
- 5) Excellent package for good heat dissipation.



Absolute Maximum Ratings: ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	-40	V
V_{GS}	Gate-Source Voltage	± 20	V
	Continuous Drain Current- $T_C=25^\circ C$	-110	A
I_D	Continuous Drain Current- $T_C=100^\circ C$	-67	
	Pulsed Drain Current ¹	-360	
E_{AS}	Single Pulse Avalanche Energy	174	mJ
P_D	Power Dissipation($T_C=25^\circ C$)	101	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
R_{eJC}	Thermal Resistance,Junction to Case	1.23	$^\circ C/W$
R_{eJA}	Thermal Resistance,Junction to Ambient	62	

Electrical Characteristics: ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
$\mathbf{BV_{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=-250 \mu\text{A}$	-40	---	---	V
$\mathbf{I_{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=-40\text{V}, V_{GS}=0\text{V}, T_j=25^\circ\text{C}$	---	---	-1	μA
$\mathbf{I_{GSS}}$	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{A}$	---	---	± 100	nA
On Characteristics						
$\mathbf{V_{GS(th)}}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250 \mu\text{A}$	-1.2	-1.6	-2.5	V
$\mathbf{R_{DS(ON)}}$	Drain-Source On Resistance	$V_{GS}=-10\text{V}, I_D=-25\text{A}$	---	3.8	5.3	$\text{m } \Omega$
		$V_{GS}=-4.5\text{V}, I_D=-15\text{A}$	---	6.4	8.3	
Dynamic Characteristics						
$\mathbf{C_{iss}}$	Input Capacitance	$V_{DS}=-20\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	---	6100	9100	pF
$\mathbf{C_{oss}}$	Output Capacitance		---	600	900	
$\mathbf{C_{rss}}$	Reverse Transfer Capacitance		---	540	810	
Switching Characteristics						
$\mathbf{t_{d(on)}}$	Turn-On Delay Time ^{2,3}	$V_{DD}=-20\text{V}, V_{GS}=-10\text{V}, R_G=6 \Omega, I_D=-45\text{A}$	---	41.6	82	ns
$\mathbf{t_r}$	Rise Time ^{2,3}		---	12.7	26	ns
$\mathbf{t_{d(off)}}$	Turn-Off Delay Time ^{2,3}		---	308	600	ns
$\mathbf{t_f}$	Fall Time ^{3,3}		---	70	140	ns
$\mathbf{Q_g}$	Total Gate Charge ^{2,3}	$V_{GS}=-10\text{V}, V_{DS}=-20\text{V}, I_D=-45\text{A}$	---	115	160	nC
$\mathbf{Q_{gs}}$	Gate-Source Charge ^{2,3}		---	16	25	nC
$\mathbf{Q_{gd}}$	Gate-Drain "Miller" Charge ^{2,3}		---	25	40	nC
Drain-Source Diode Characteristics						
$\mathbf{V_{SD}}$	Source-Drain Diode Forward Voltage	$V_{GS}=0\text{V}, I_S=-1\text{A}, T_j=25^\circ\text{C}$	---	---	-1	V

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

Typical Characteristics: ($T_c=25^\circ C$ unless otherwise noted)

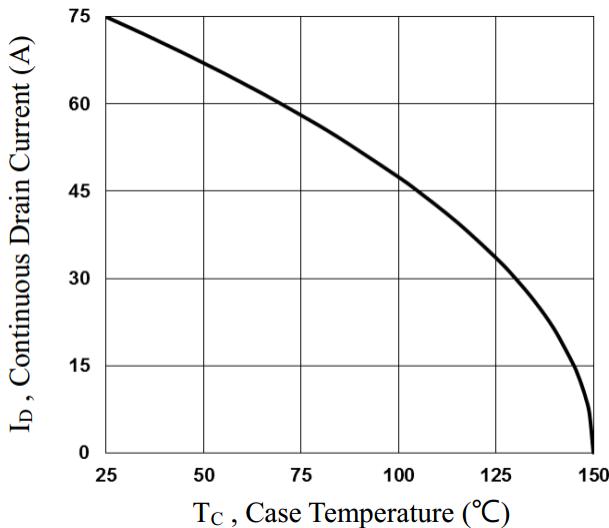


Fig.1 Continuous Drain Current vs. T_c

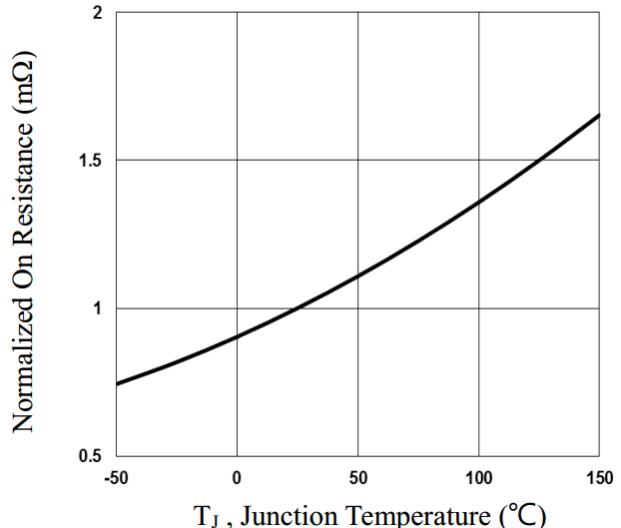


Fig.2 Normalized $R_{DS(on)}$ vs. T_j

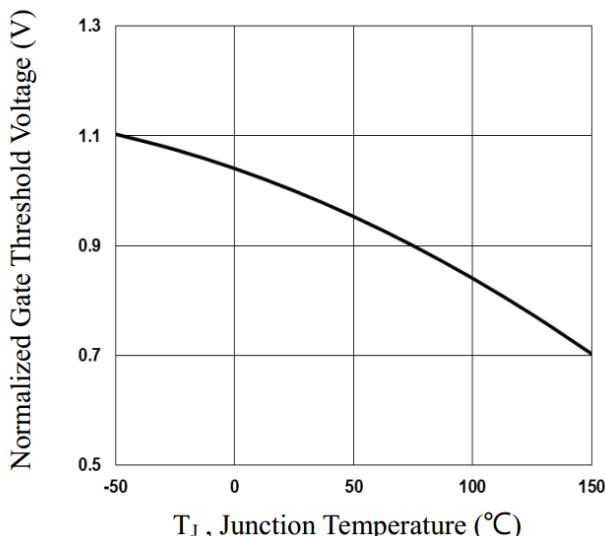


Fig.3 Normalized V_{th} vs. T_j

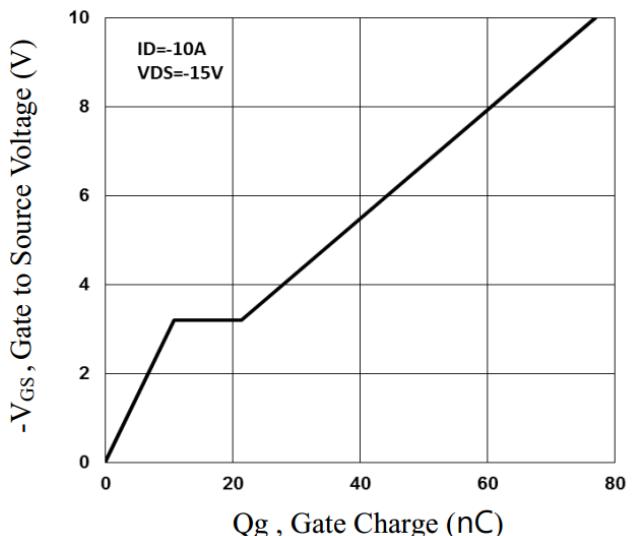
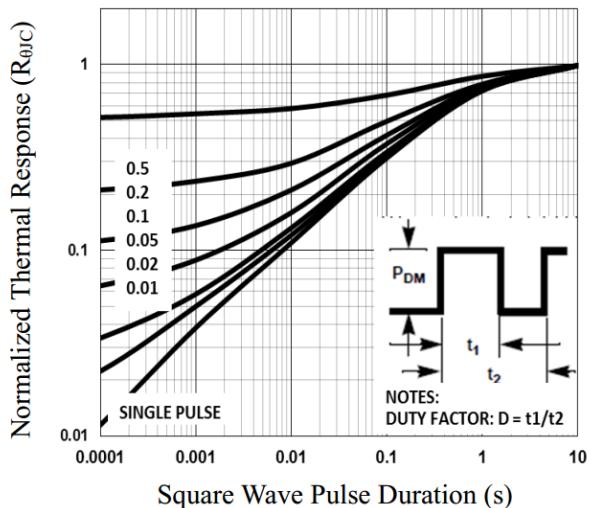
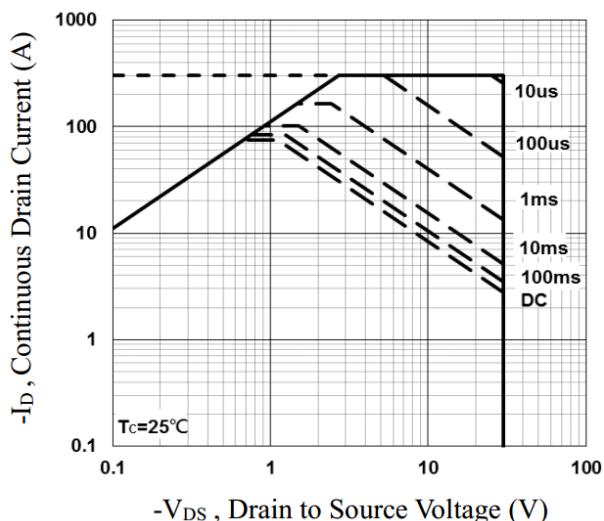
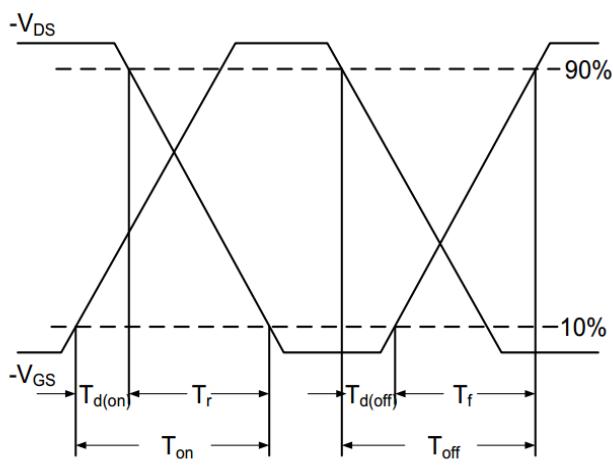
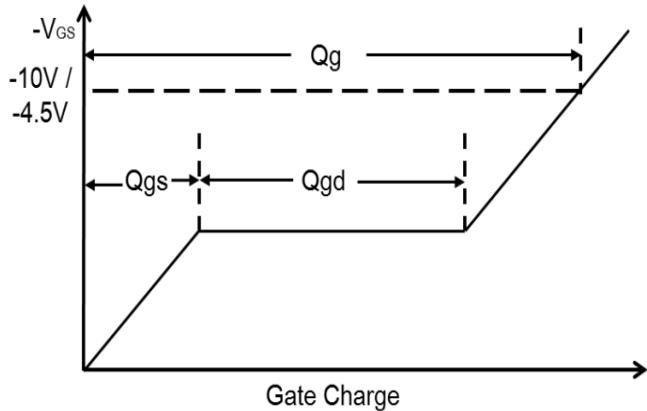


Fig.4 Gate Charge Waveform


Fig.5 Normalized Transient Impedance

Fig.6 Maximum Safe Operation Area

Fig.7 Switching Time Waveform

Fig.8 Gate Charge Waveform